Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Envy Recline23 TouchSmart Beats SE All-in-One PC</th>
</tr>
</thead>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board, USB Board, Power Board, Touchpad Module, TP Board, WLAN Card, RAM Module (x2)</td>
<td>8</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries <strong>RTC Battery</strong></td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps <strong>Touch LCD display</strong></td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers
Components, parts and materials containing radioactive substances 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>TORX T8</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassembly Ram Door
2. Disassembly HDD & Dongle
3. Disassembly Ram Shielding
4. Disassembly DDR Ram*2
5. Disassembly Rear cover sub assay
6. Disassembly Camera Module, PCB modules
7. Disassembly Thermal module Fan
8. Disassembly Mother board shielding
9. Disassembly WLAN Card
10. Disassembly Thermal module
11. Disassembly CPU
12. Disassembly Hinge Cap L&R
13. Disassembly Stand unit
14. Disassembly Support bridge
15. Disassembly Mother Board + USB 3.0 PCB and RTC battery
16. Disassembly Separate the USB 3.0 PCB from M/B
17. Disassembly Speaker left & right side
18. Disassembly Base Pan sub assay
19. Disassembly Loosen FPC
20. Disassembly LCD Panel

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Disassembly Ram Door
3.22 Disassembly HDD & Dongle
3.23 Disassembly Ram Shielding

3.24 Disassembly DDR Ram*2

3.25 Disassembly Rear cover sub assay

3.26 Disassembly Camera Module, PCB modules

3.27 Disassembly Thermal module Fan

3.28 Disassembly Mother board shielding

3.29 Disassembly WLAN Card

3.30 Disassembly Thermal module
3.31 Disassembly CPU

3.32 Disassembly Hinge Cap L&R

3.33 Disassembly Stand unit

3.34 Disassembly Support bridge

3.35 Disassembly Mother Board + USB 3.0 PCB and RTC battery

3.36 Disassembly Separate the USB 3.0 PCB from M/B
3.37 Disassembly Speaker left & right side
17. Disassembly Speaker Left side (3Pcs M3.0 screw) & Right side (2Pcs M4.0 screw)

3.38 Disassembly Base Pan sub assay
18. Disassembly Base pan sub assy = 11Pcs M3.0 screw

3.39 Disassembly Loosen FPC
19. Disassembly Loosen FPC

3.40 Disassembly LCD Panel
20. Disassembly LCD Panel